Spec. No. : HE6537 Issued Date : 1992.11.25 Revised Date : 2002.02.22

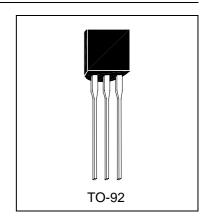
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# **HSD965**

NPN EPITAXIAL PLANAR TRANSISTOR

# **Description**

The HSD965 is suited for use as AF output amplifier and flash unit.



# **Absolute Maximum Ratings**

| Maximum Temperatures  |                |
|---|----------------|
| Storage Temperature   |                |
| Junction Temperature  | 150 °C Maximum |
| Maximum Power Dissipation                                   |                |
| Total Power Dissipation (Ta=25°C)                           | 750 mW         |
| <ul> <li>Maximum Voltages and Currents (Ta=25°C)</li> </ul> |                |
| VCBO Collector to Base Voltage                              | 40 V           |
| VCEO Collector to Emitter Voltage                           |                |
| VEBO Emitter to Base Voltage                                | 7 V            |
| IC Collector Current (Continuous)                           | 5 A            |
| IC Collector Current (Peak PT=10mS)                         | 8 A            |

## **Characteristics** (Ta=25°C)

| Symbol    | Min. | Тур. | Max. | Unit | Test Conditions       |  |
|-----------|------|------|------|------|-----------------------|--|
| BVCBO     | 40   | -    | -    | V    | IC=100uA, IE=0        |  |
| BVCEO     | 20   | -    | -    | V    | IC=1mA, IB=0          |  |
| BVEBO     | 7    | -    | -    | V    | IE=10uA, IC=0         |  |
| ICBO      | 1    | -    | 0.1  | uA   | VCB=10V, IE=0         |  |
| IEBO      | 1    | -    | 0.1  | uA   | VEB=7V, IC=0          |  |
| *VCE(sat) | 1    | 0.35 | 1    | V    | IC=3A, IB=100mA       |  |
| *hFE1     | 230  | -    | 800  |      | VCE=2V, IC=0.5A       |  |
| *hFE2     | 150  | -    | •    |      | VCE=2V, IC=2A         |  |
| fT        | -    | 150  | -    | MHz  | VCE=6V, IE=50mA       |  |
| Cob       | -    | -    | 50   | pF   | VCB=20V, f=1MHz, IE=0 |  |

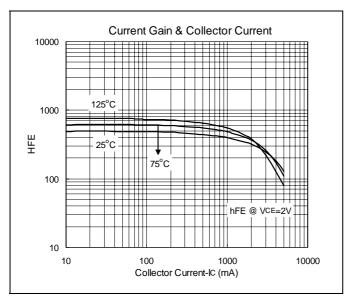
\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

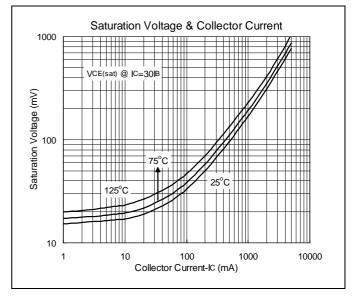
## **Classification Of hFE**

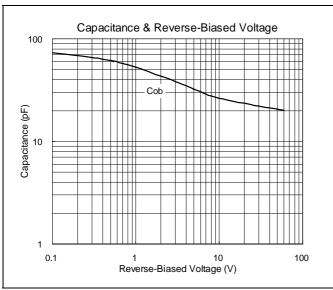
| Rank  | Q       | R       | S       |  |
|-------|---------|---------|---------|--|
| Range | 230-380 | 340-600 | 560-800 |  |

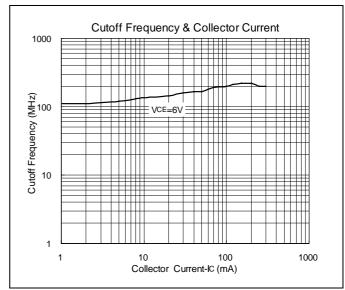
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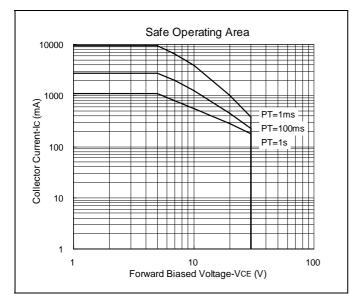
### **Characteristics Curve**

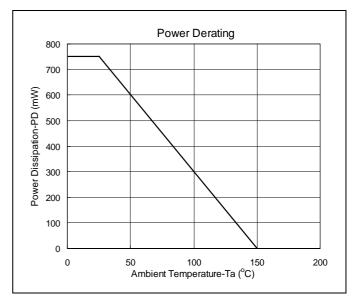










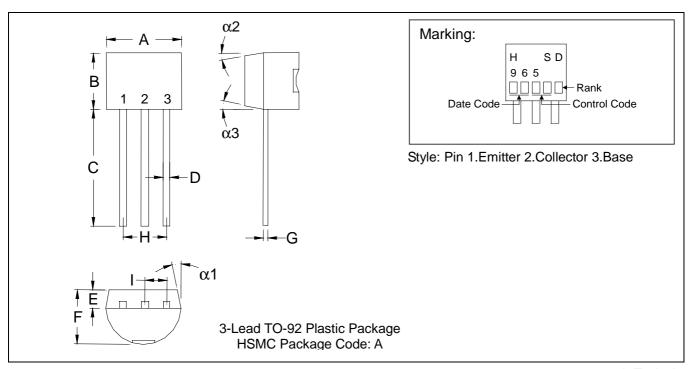




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## **TO-92 Dimension**



\*: Typical

| DIM | Inches |         | Millimeters |       | DIM   | Inches |         | Millimeters |       |
|-----|--------|---------|-------------|-------|-------|--------|---------|-------------|-------|
|     | Min.   | Max.    | Min.        | Max.  | ווועו | Min.   | Max.    | Min.        | Max.  |
| Α   | 0.1704 | 0.1902  | 4.33        | 4.83  | G     | 0.0142 | 0.0220  | 0.36        | 0.56  |
| В   | 0.1704 | 0.1902  | 4.33        | 4.83  | Ι     | -      | *0.1000 | 1           | *2.54 |
| С   | 0.5000 | -       | 12.70       | -     | I     | -      | *0.0500 | -           | *1.27 |
| D   | 0.0142 | 0.0220  | 0.36        | 0.56  | α1    | -      | *5°     | -           | *5°   |
| Е   | -      | *0.0500 | -           | *1.27 | α2    | -      | *2°     | -           | *2°   |
| F   | 0.1323 | 0.1480  | 3.36        | 3.76  | α3    | -      | *2°     | -           | *2°   |

Notes: 1. Dimension and tolerance based on our Spec. dated Apr. 25,1996.

- 2. Controlling dimension: millimeters.
- 3. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
- 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

#### Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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